

ABSTRACT

ADHESIVE TAPE FOR ELECTRONIC PARTS

Disclosed is an adhesive tape which can bond electronic parts at the environs of a lead frame, such as leads, diepads
5 and radiant plate semiconductor chips, to each other and is superior in adhesiveness, thermal resistance and electrical properties. The adhesive tape is produced by coating on one side or both sides of a thermal resistant film an adhesive composition comprising an acryl resin, a mixed epoxy resin of
10 a bisphenol A-type epoxy resin and a cresol novolak epoxy or a phenol novolak epoxy resin, a maleimide compound containing at least two intramolecular maleimide groups, an aromatic diamine compound, an epoxy-containing liquid silicon resin and an organic or inorganic filler and drying it.